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# onsemi

# Next-Gen Motor Drives: Exploring SiC

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PSG EMEA Marketing







**Motor Drive requirements and limiting factors** 

# Requirements for a Drive and for Switches in Drives' Inverter

## **Drive requirements**

- Low-cost solution
- Robust
- Long lifetime
- EMI compliant

## Minor factors

- Efficiency
- Size

## **Electronic Switches requirements**

- Short Circuit rated
- Peak current capability
- Easy implementation/design



# **Motor Limiting factors**

- The motor winding is used as a low pass filter for the high frequency content generated by the switching inverter.
- Motor winding wires are isolated with a varnish.
- High dV/dt cannot be handle by the varnish.

### **Present Solution:**

- Limit dV/dt by increasing the gate resistor.
- Integrated solutions (Switches+Drivers in one package) are less sensible to noise.







SiC performances vs IGBT

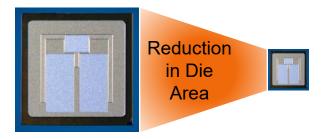
# **Comparison of Material Properties**

§ Critical Electric Field along c-axis for vertical power devices

Key Material Properties					
Electrical Property	Silicon (Si)	Silicon Carbide (4H-SiC)			
Bandgap (eV)	1.12	3.26			
Critical Electric Field (MV/cm)	0.3	3.0 <sup>§</sup>			
Saturated Electron Velocity (× 10 <sup>7</sup> cm/s)	1	2			
Thermal Conductivity (W/cm·K)	1.3	3.3			

90% Lower Resistance Higher Voltage Devices SiC Epi layer 90% Reduction in Epi layer Thickness Silicon Epi layer Silicon Substrate

- **Higher Current Density**
- **Faster Switching**



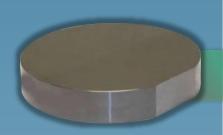
- Faster Heat Removal
- **Less Complex Cooling**

Reduction in Heatsink Volume



# SiC Supply Assurance: From Substrate to Modules

**SiC Substrates** 



 150/200mm SiC wafering internal in onsemi today

> Hudson, NH, USA (Roznov, CZ)

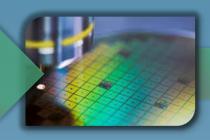
SiC Epi



 150/200mm SiC epi internal in onsemi today

> Bucheon, KR Roznov, CZ

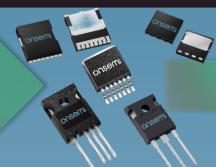
SiC Fab



Fabs ready today for 150mm →200mm migration

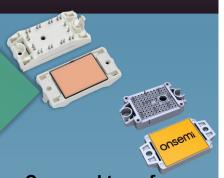
> Bucheon, KR (Roznov, CZ)

SiC Devices / Die



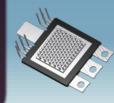
- Broad base of packages
- Die only & metal options
- Auto & Industrial devices

**SiC Modules** 



- Case and transfer molded options
- Full portfolio of half & full bridge modules
- Single & dual cooling, direct & indirect

**Binh Duong Province, VN** Suzhou, CN Shenzhen, CN Seremban, MY



onsemi's end to end capabilities drive superior performance and quality

# The Power Semiconductor Market Outlook:



## Power Semiconductor Market by 2028

- Total power marked forecasted to be \$41B
- SiC expected to be 23% or \$9.4B
- (Less than 20% is forecasted to be on 8inch..)
- GaN is expected to be \$2.2B
- Parts of GaN market can be addressed with SiC Cascode

#### Automotive market ~70%

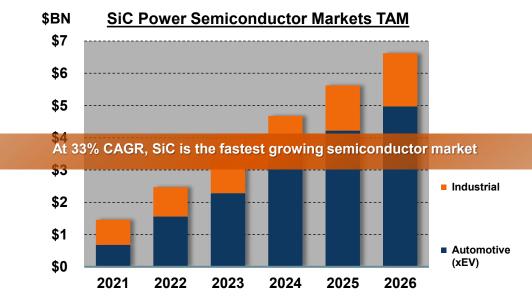
- eV Traction is KEY!
- OBC, DCDC & BMS is significant
- Adjacent such as Aircon

#### Industrial Market ~30%

- Renewables: Solar & Wind
- Energy infrastructure ESS, UPS & EV Charging
- + Servo Drives, Plasma cutting, Welding, Water Cookers, CT scanners +++



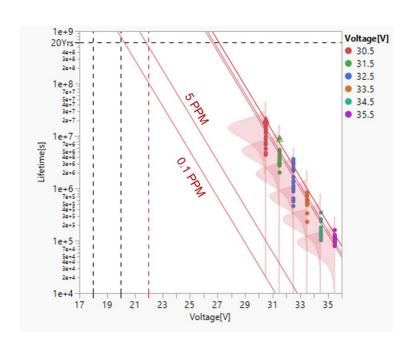
2021 & 2024 SIC DEVICE MARKET SHARE



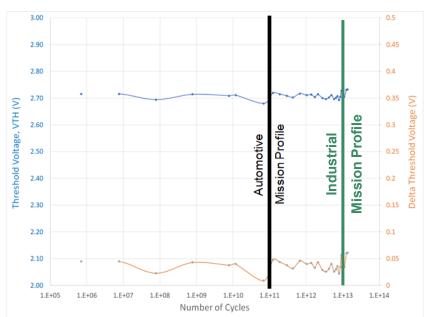


# **Generation M3S Reliability**

#### Intrinsic Gate Lifetime at 175°C



## Gate Threshold, Vth



Rdson shift **Mission Profile** Industrial Mission Profile Rdson @30A, Vgs18V increase (%) ∙Vgs=-3V/18V Vgs=-8V/18V 1.00E+11 1.00E+13 1.00E+07 Total stress cycles

At maximum operational  $V_{GS} = 18V$ , onsemi gate oxides demonstrate failure rates well below 1PPM achieved from optimized process and burn-in

Only 50mV of threshold voltage shift observed after 1E11 cycles of gate switching (-3V to 18V) at 25°C.

Only 1% of Rdson shift observed after 1E13 cycles of gate switching (-3V to 18V) at 25°C.

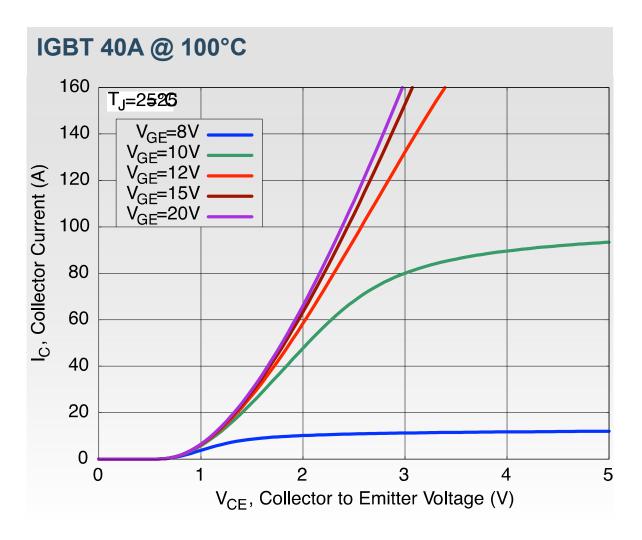


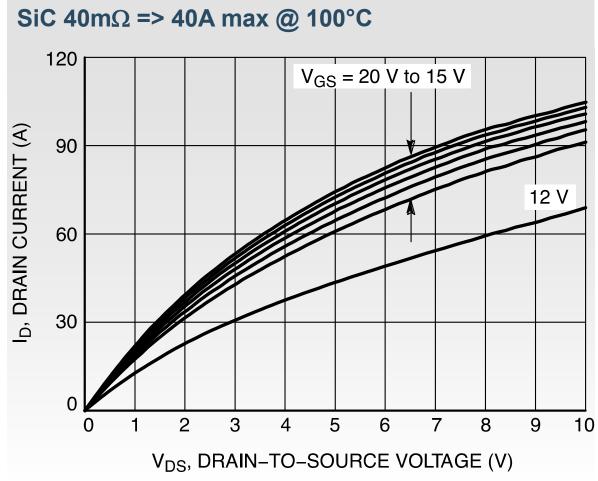




Why SiC in motor drives?

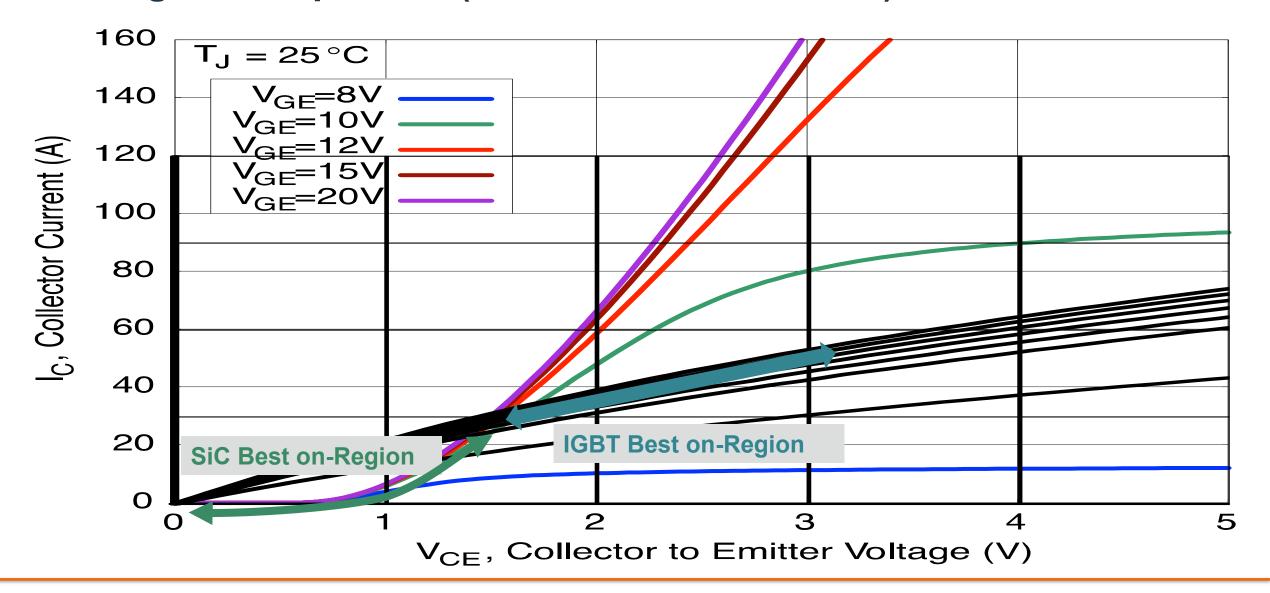
# On-Region comparison (for 40A device at 100°C)





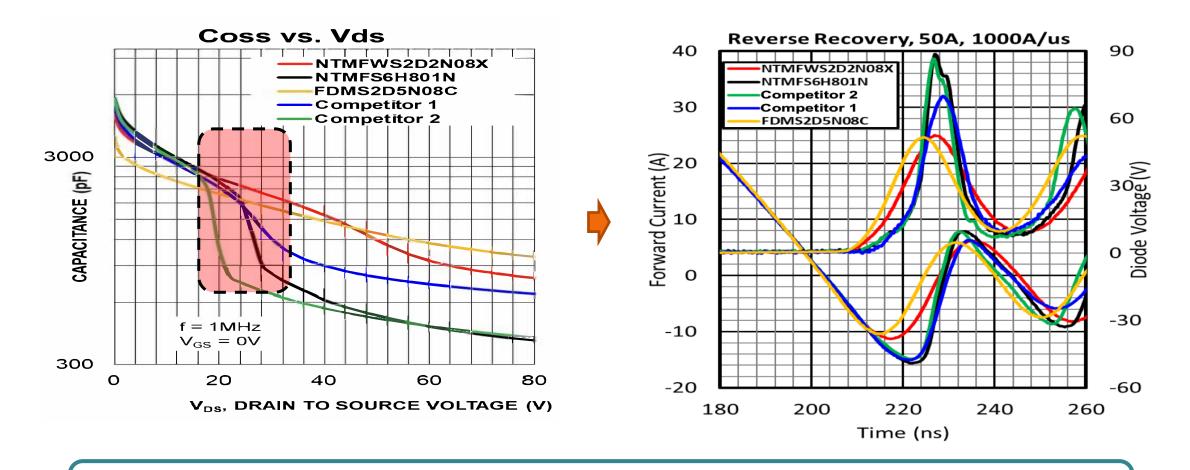


# On-Region comparison (for 40A device at 100°C)





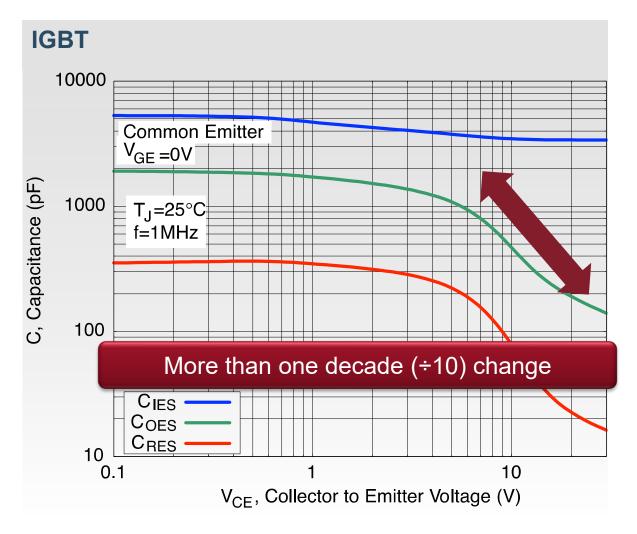
# Coss and Qrr optimization - T10 80V (NTMFWS2D2N08X)

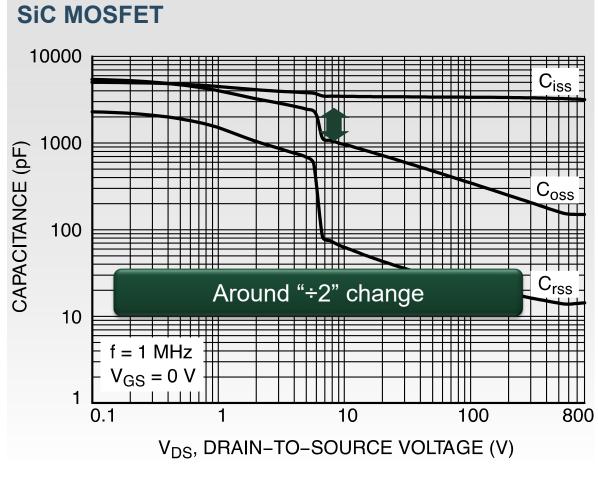


The larger the step in Output Capacitor, the higher overvoltage and steeper the reverse recovery



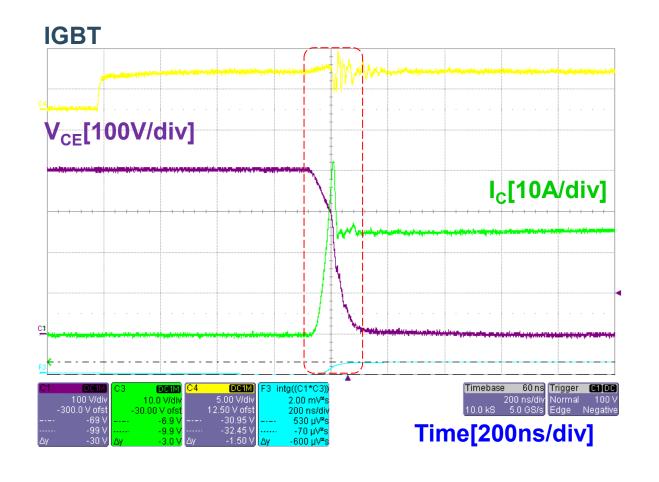
# **Output Capacitor comparison**

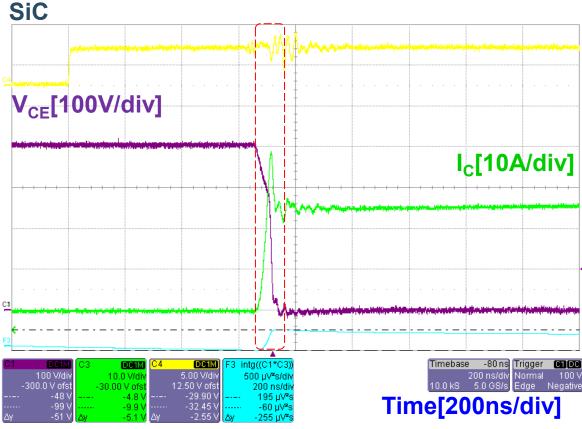






# Switching Performances (@ same maximum dV/dt)





- Lower peak current or lower reverse current
- No tail current
- Lower transition duration ➤ Lower losses





# onsemi IPM All in One Technology

## Substrate

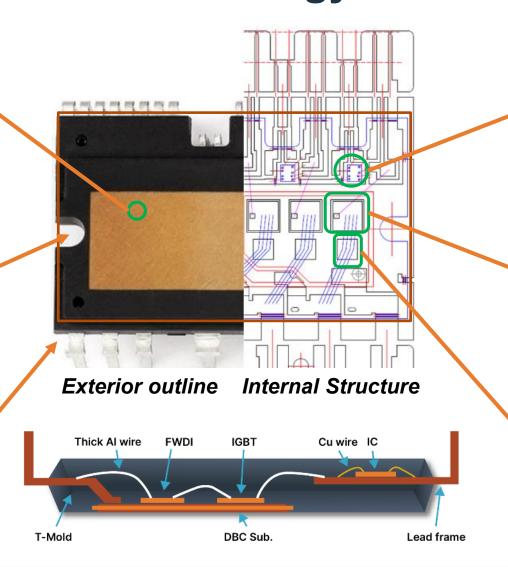
**DBC substrate (AIN/AI2O3) IMST** substrate **Ceramic substrate** Full Mold PKG

# **Passive** Component

**Shunt resistor NTC** thermistor **Ceramic capacitors / Resistors** 

# **Variety Topology**

3-phase topology PFC: Interleaved / Bridge-less / Boost



## **Gate Driver Unit**

**IGBT/MOSFET** control **Protection function** 

## **Power Switch**

650V FS3/4 Trench SCR IGBT 1200V FSII Trench SCR IGBT **Super Junction SF2/3 MOSFET Planar UniFET MOSFET** 650V FS4 RC IGBT 1200V FS7 IGBT **1200V SIC MOSFET** 

## **Power Diode**

800V/1600V Hyper Fast Diode 650V /1200V Extreme Fast Diode 650V SiC Diode 1200V Gen7 Diode



# IGBT SPM®31 (Mini)

#### **Features**

- · Pin compatible with 'M' Competitor Mini DIP
- · Advanced Trench SC rated IGBT
- Very low thermal resistance with DBC substrate
- Built-in real NTC on DBC(Option), bootstrap diodes
- · No side dummy for more creepage

#### **Benefits**

- · All these part is pin-compatible
- Wide product coverage; 20A~50A/650V, 15~35A/1200V
- Superior thermal performance and low loss

## **Specifications**

#### 1200V Line up

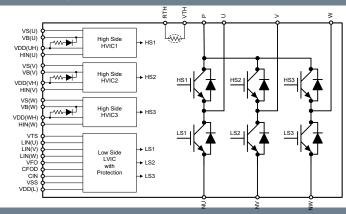
Product	Voltage	Current	V <sub>CE(SAT)</sub> typ.	IGBT	Substrate	Remark
NFAM1512L7B	1200V	15A	1.50V	FS7	DBC(Al2O3)	
NFAM2512L7B	1200V	25A	1.50V	FS7	DBC(Al2O3)	MP
NFAM3512L7B	1200V	35A	1.60V	FS7	DBC(Al2O3)	

#### 650V Line up

Product	Voltage	Current	V <sub>CE(SAT)</sub> typ.	Substrate	Status
NFAM2065L4B(T)	650V	20A	1.6V	DBC(Al2O3)	MP
NFAM3065L4B(T)	650V	30A	1.6V	DBC(Al2O3)	MP
NFAM5065L4B(T)	650V	50A	1.65V	DBC(Al2O3)	MP

#### T: NTC option

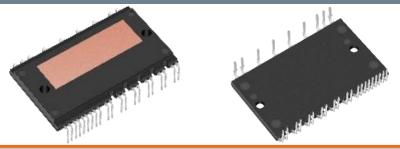
#### **Block Diagram**



## **Target Applications**

- HVAC, Heat Pumps, Commercial Air conditioner
- **Industrial Pumps**
- Variable frequency drive
- Servo drive, Robotics
- Industrial Fans

## Package ; 54.5 mm × 31 mm × 5.6 mm





# SiC SPM®31 (Mini)

#### **Features**

- 1200V M3P SiC MOSFET (Vgs: 0V ~ 18V)
- Miller Clamp function into gate drivers
- Pin compatible with 'M' Competitor Mini DIP & onsemi IGBT SPM31
- · Low thermal resistance with DBC substrate
- Built in bootstrap circuit
- NTC thermistor for junction temperature monitoring
- Temperature sensing and output voltage function in LVIC
- No side dummy for more creepage
- · High power density, High efficiency, Fast switching capability

## 1200V Line-up

Product	Voltage	Rds(on)	Substrate	Remark
NFAM5312SCBUT	1200V	53 mΩ (40A)	DBC	
NFAM3812SCBUT	1200V	38 mΩ (50A)	DBC	MP
NFAM2512SCBUT	1200V	25 mΩ (70A)	DBC	

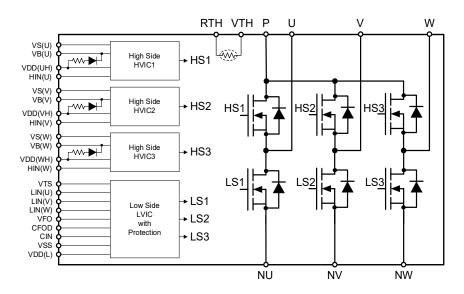
### **Target Application**

Servo Motor

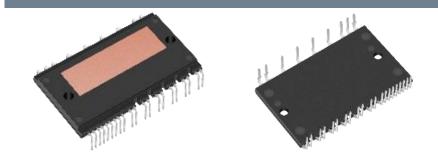
Industrial Inverter

• HVAC, EC Fan

## **Block Diagram**

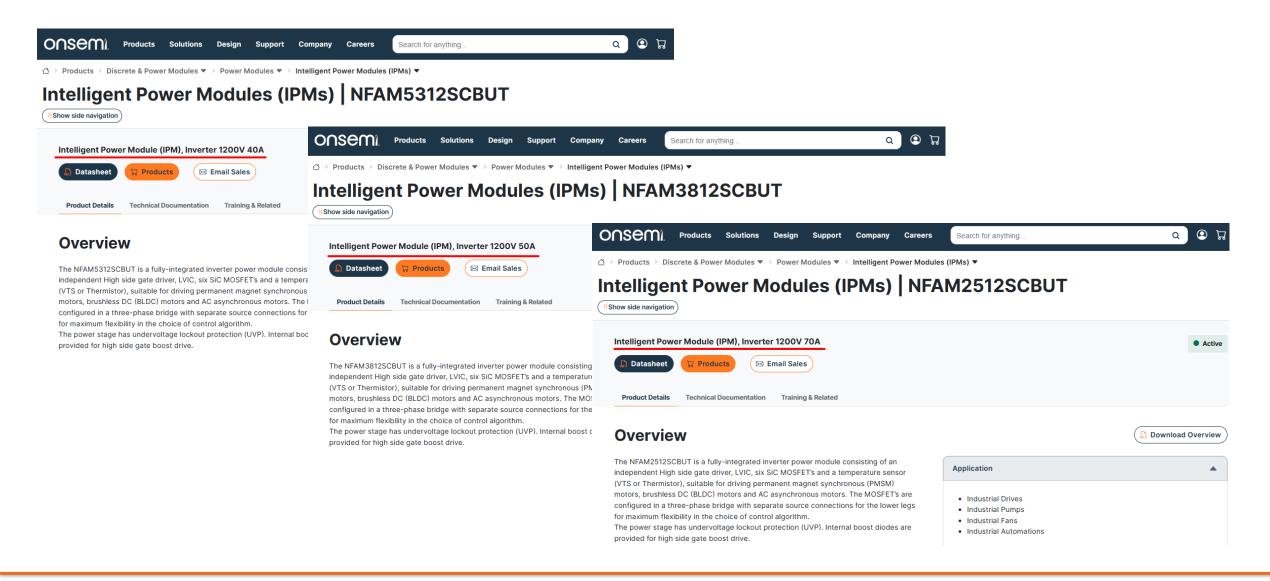


## Package: 54.5 mm $\times$ 31 mm $\times$ 5.6 mm





## SiC SPM31 Released





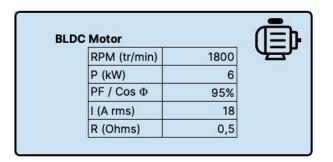


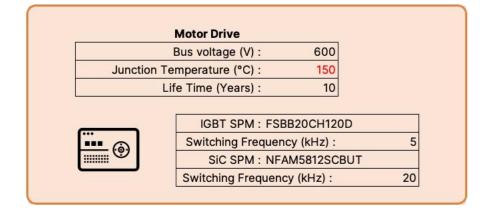


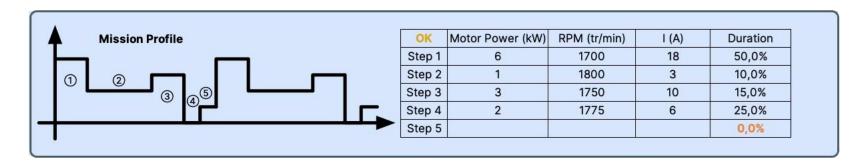
Tool to compare IGBT vs SiC in motor drive applications

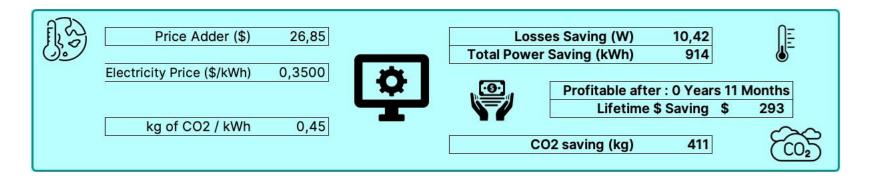
Ask onsemi support for assistance to use it.

# **SPM SiC Power saving** onsemi





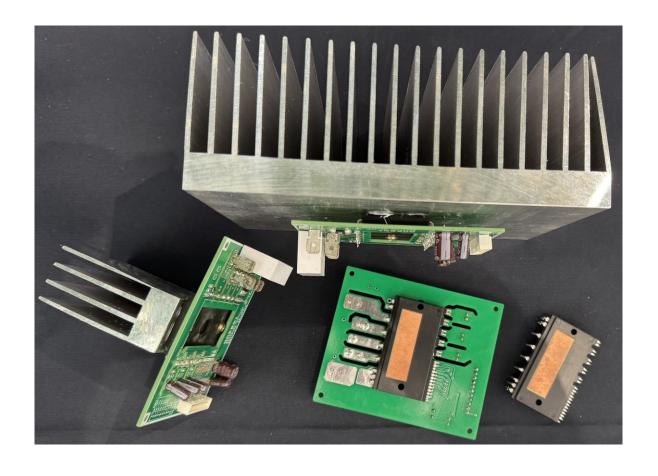








# **Industrial Motor Drive**



- SPM31 IGBT vs SiC
  - For Heat Pump application: 7kW motor
  - Same Junction Temperature
  - Same conditions

➤ Heatsink ratio between IGBT and SiC

## Conclusion

- onsemi provides IGBT solutions for motor drive applications in discrete and modules with or without drivers included.
- In onsemi, we believe in SiC for medium- and high-power drive applications
- We have proven and reliable solutions for SiC Discrete and Module
- SiC MOSFETs will remain more expensive than Silicon IGBTs

For motor drive, Cost and dV/dt are critical. SiC modules have same dV/dt as IGBT ones.

- Even if SiC Motor Drives modules will be more expensive, onsemi demonstrates:
  - The cost of ownership will be lower with SiC
  - SiC Drives Return On Investment is positive rapidly...



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